

Gas purifying systems

Gas chromatography, environment analysis, pharmaceutical and biotechnical applications

Oxygen, moisture and hydrocarbons are the three main chemical impurities which have to be reduced before the gases are used for analytical purposes. Moisture and oxygen carrier gas limit the life span of the GC chambers, while hydrocarbons cause "ghost peaks" in chromatogram. This leads to poor results and inadequate reproducibility.

Semiconductor technology

In the semiconductor industry, oxygen and carbon are spurious substances in the construction of the individual layers which impair the electrical charateristics of the components. Both these elements from chemical compounds with virtually all other substances and are therefore contaminate the semiconductor layers.

Welding technology

The reduction of oxygen and moisture in welding gas lead to narrower more stable WIG arc and a steadier MIG arc which causes less splashing. This in turn produces smoother, narrower seams and better flowing of the filler material on the seam flanks. The fusion penetration is more intensive and there is less tendency to form pores. In addition, cost advantages result from the increased welding speed and reduction is finishing work.

Excimer-Laser technology

Excimer lasers operate with radiation in the ultra-violet spectrum. Through gas discharges, stimulated inert-gas and halogen compounds (excimers) are formed, which disintegrate into their original elements after transmission of the UV laser beam. Any impurities which inhibit the electrical stimulation or which react chemically with the halogens (fluorine or hydrogen chloride) tend to disrupt the process. These are primarily moisture and hydrocarbons.

Container:			
		Oxisolo in	Oxigoto Inall
Absorbtion cap	acity:		
02	I	0.1	0.1
H ₂ O vapour	- 1	0.5	0.5
C ₂ H ₆	mg	-	-
C ₃ H ₈	mg	-	-
Higher HC	mg	-	-
Oil traces	g	-	-
H ₂ S	g	-	-
NO	g	-	-
SO ₂	g	-	-
Hg	g	-	-
Guaranteed final purity		O_2 < 5 ppb ³⁾	O_2 < 5 ppb ³⁾
		H ₂ O < 30 ppb	H ₂ O < 30 ppb
Flow rate max.	m³/h	1	1
Pressure max.	bar	10 in low-	
Length	mm	125	130
Diameter	mm	29	30
Filled under Ar		-	-
Order. No.		-	-
Filled under He	(1و	792.	792.
Order. No.		40225	52099
Filled under CO) ₂ ¹⁾	-	_
Order. No.		-	-

- 1) Delivery in packs of two cartridges
- 2) Manufacture on request
- 3) Not valid for the LP-mounting unit for the installa

Room temperature Adsorbers

Description	Areas of application	Contamination		
OXISORB®	Precious gases, nitrogen, hydrogen, carbon monoxide, saturated hydrocarbons, no oxygen	Oxygen, moisture		
Hydrosorb	Precious gases, nitrogen, hydrogen, carbon monoxide, carbon dioxide, saturated hydrocarbons, halogenated hydrocarbons, compressed air, oxygen	Moisture (If the gases mentioned above are dry, carbon dioxide is adsorbed)		
ACCOSORB®	Precious gases, nitrogen, hydrogen, carbon monoxide, carbon dioxide, saturated hydrocarbons, halogenated hydrocarbons, compressed air, no oxygen	Hydrocarbons, oil vapour		
SULFOSORB®	Precious gases, nitrogen, hydrogen, carbon monoxide, carbon dioxide, saturated hydrocarbons, compressed air, no oxygen	Mercaptan, carbonyl sulphide, carbon disulphide, hydrogen sulphide, sulphur dioxide, nitrogen monoxide		



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that os dig the state of the st	ACOSORB®	sulfosore	Oksoro Okuminimi	Hydrosoft Hydros	ACCO SORD	SIIFOSORO	2.70 stiedle	2.20 dosaro	e three	5.50 right	270 Allingolp
-	-	-	9	-	-	-	65	-	∞	41	_
1	-	_	45	100	-	-	-	430	-	-	270
-	1	-	-	-	55	-	-	-	-	-	-
-	180	-	-	-	9000	-	-	-	-	-	-
-	> 180	-	-	-	9000	-	-	-	-	-	-
-	8	- 0.50	- 0.50	0.50	450	28	-	-	_	_	_
	-	0.50	0.50	0.50	-	2.8	-	-	-	-	-
_	_	0.50	0.50	0.50	_	2.6	-	_	_	_	_
	_	0.50	0.50	0.50	_	20	_		_	_	
	_	e.g.	$O_2 < 5 \text{ ppb}^{3}$	_	_	_	_	_	_	_	_
H ₂ O < 20 ppb	HC < 10 ppb ³⁾		$H_2O < 30 \text{ ppb}$	H ₂ O < 20 ppb	HC < 10 ppb	$H_2S < 1 ppb$	O ₂ < 5 ppb	H ₂ O < 10 ppb	O ₂ < 1ppm	O ₂ < 5 ppb	H ₂ O < 10 ppb
1	1	1	10	10	10	10	100	100	100	100	100
200 in high-r	l oressure mou	ntina units	10	10	10	10	20	20	20	200	200
125	120	125	1170	1170	1170	1170	1590	1590	1590	1530	1530
29	29	29	71	71	71	71	159	159	159	160	160
-	-	_	792.	792.	792. ²⁾	792. ²⁾	-	_	-	-	_
-	-	-	30893	54831	54832	54834	-	-	-	-	_
792.	792.	792.	-	-	-	-	-	-	-	-	-
40226	40228	40229	-	-	_	_	_	-	-	_	_
796. ²⁾	-	-	-	-	-	-	_	-	_	-	_
07926	-	-	-	-	-	-	-	-	-	-	_

ionin gas supply systems (< 100 ppb)

Disposable cartridges				
Description	Areas of application	Contamination		
EXCISORB®-F	Fluorine containing mixtures	Fluorine		



Low-pressure (LP) holder systems for small cartridges

LP holder for mounting in pipings	LP wall holder	LP combination VARIOSORB vertically	LP combination VARIOSORB horizontally	
Upper section and lower section and pipe connection nut made black plastics (HOSTAFORM®); a set of spare O rings is included in the supply scope. Connections are offered separately. Lower section stainless steel, upper section and pipe connection nut made of black plastics (HOSTAFORM®). A wall bracket (incl. screws and plugs) for wall mounting is as well as a set of spare O rings are included in the supply scope. Connections are offered separately.		Connecting adapter and union nut made of black plastics (HOSTAFORM®). The connecting unit allows combinations with LP wall holder as well as operating one upon the other of two or more small cartridges for removal of different impurities out of the gas stream.	Quick coupling. Spiral and clamping-ring connection made of stainless steel. The connecting unit allows combinations with LP wall holder as well as operating one after another of two or more small cartridges for removal of different impurities out of the gas stream.	
Ordering No. 795 10733	Ordering No. 794 24364	Ordering No. 794 24363	Ordering No. 770 33042	
Type of connection	Type of connection			

High-pressure holder systems for small cartridges

HP Housing PN 200

Housing of stainless steel for mounting piping: a bracket for wall mounting is also supplied. For a system pressure up to 200 bar the HP holder PN 200 is required. If a final purity < 1 ppb is to be obtained, the HP holder (also for system pressures < 10 bar) must be used. Connections are offered seperately.



	Anschlusstyp	Ordering No.
	ES 3 mm ²⁾	0291 281
	ES 6 mm ²⁾	0291 280
	ES 1/4'' ²⁾	770 31374
i	ES 1/8''2)	795 10829
	ES VCR-Verschraubung	auf Anfrage
	2) Klemmringverschraubung	

²⁾ Klemmringverschraubun



Low-pressure (LP) holder systems for large cartridges

Single holder

2 brackets for wall mounting including screws an plugs; the inlet and outlet valves is closed with a NPT 1/4" blind plug. After removal of the blind plug the pipe screw connections with NPT 1/4" external thread can be screwed in. Connections are



1

offered separately.

Type of connection	Ordering No.
ES 6 mm ²⁾	0291 280
ES 8 mm ²⁾	0049 033
ES 1/4'' ²⁾	770 31374
ES 1/8'' ²⁾	795 10829
FS VCR-connection	on request

2) Clamp ring connection stainless steel

Ordering No.

796 04537

Wall holder with flushing unit

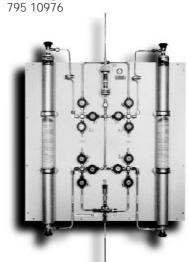
Complete wall holder with flushing unit for flushing connection piping after exchange of a cartridge; consisting of safety-, shut-off-, and flushing valves, fittings are preassembled on the aluminium console: with bracket for wall mounting; materials: copper, brass chromium-plated. Screw connection is pre-assembled with ES 8 mm pipe strut.

Ordering No. 796 04822

Double flushing holder with optical load indication

Double flushing holder for flushing connection pipes after cartridges exchange with optical load indication; consisting of two large aluminium cartridges combined with OXISORB® small cartridges of glass as load indication, safty-, shut-off-, and flushing valves; cartridges and fittings preassembled on aluminium console; with brackets for wall mounting; materials: copper, brass chromium-plated. Screw connection is pre-assembled with ES 8 mm clamping-ring connection.

Ordering No.



Large cartridge: OXISORB®

Large cartridge OXISORB® R 20

Large cartridge OXISORB® R 20 Extrapur





Process:
Chemisorption:
oxygen and moisture
are **chemically bound**on the adsorbant
material and therefore
permanently removed
from the stream of
gas. The adsorption
process is dependent
on the ambient
temperature and
pressure.